

# SOLDER WIRES OF THE KS-SERIES

No-Clean solder wires with clear residues

#### DESCRIPTION

Stannol KS-Series electronic solder wires have been designed for special requirements of lead-free soldering. They meet all demands of industrial manufacturing as well as for rework and repair.

Stannol solder wire KS115 contains a rosin-free, halide activated synthetic resin.

The Stannol KS100 is based on the same synthetic resin however it is halide free activated.

All mentioned flux types are an excellent combination of high activity at thermal stress with amber bright and electrically safe residues.

The flux formulations KS115 is classified to DIN EN 29454-1 Type 1.2.2.B. Due to its high activity (1.5%), the flux is classified as REM1 to IEC 61190-1-3.

The KS100 is classified to DIN EN 29541- Type 1.2.3.B and REL0 to IEC 61190-1-3.

#### **CHARACTERISTICS**

#### The synthetic resins offer more advantages as natural rosin:

- active flux (fast wetting of solder pads and pins, shorter cycle times)
- bright amber residues (low thermal decomposition at soldering temperatures, optical impression ok)
- **solid residues** (high softening point, chemical and physical safety)
- **low fuming** (low decomposition and evaporation at high temperatures, low contamination of work place and around the solder joint)
- low spitting (high viscosity of the flux reduces spitting, low contamination)

#### APPLICATION

Stannol solder wire KS115 is designed for use with robotic and manual soldering for electric and electronic devices. Flux residues may remain uncleaned. This must be examined in individual cases, where environmental stress is applied to the circuit.

If cleaning is necessary for optical or technical reasons, we recommend the use of the cleaner Stannol Flux-Ex 500.

## PHYSICAL PROPERTIES OF THE FLUX

GENERAL PROPERTIES		KS100	KS115	
Flux type:	EN 29454-1	1.2.3 (F-SW33)	1.2.2 (F-SW28)	
	IEC 61190-1-3	RELO	REM1	
Flux content:	EN 12224	3,0 weight % ± 0,3		
Halide content:	EN 29455-6	0,0%	1,5%	
Corrosivity:	EN 29455-15	none		
Surface Insulation Resistance:	85 °C / 85 %r.F.,	>10 <sup>8</sup> W		
	IPC TM 650 2.6.3.3			
Standard alloys acc. to ISO 9453:2006 with micro additives <0,05%	l	lead-free (FLOWTIN-Series)		
		FLOWTIN TC (Sn99Cu1)		
	F	FLOWTIN TSC (Sn95Ag4Cu1)		
	FL	FLOWTIN TSC305 (Sn96Ag3Cu1)		
Available diameters:		from 0,3 mm		
Available reel sitze:		250 g, 500 g, 1 kg		

Other alloys, flux contents or reel sizes are available on request.

### **HEALTH AND SAFETY**

Before using please read the material safety data sheet carefully and observe the safety precautions described.

#### NOTICE

The above values are typical and represent no form of specification. The Data Sheet serves for information purposes. Any verbal or written advise is not binding for the company, whether such information originates from the company offices or from a sales representative. This is also in respect of any protection rights of third parties, and does not release the customer from the responsibility of verifying the products of the company for suitability of use for the intended process or purpose. Should any liability on the part of the company arise, the company will only indemnify for loss or damage to the same extent as for defects in quality.